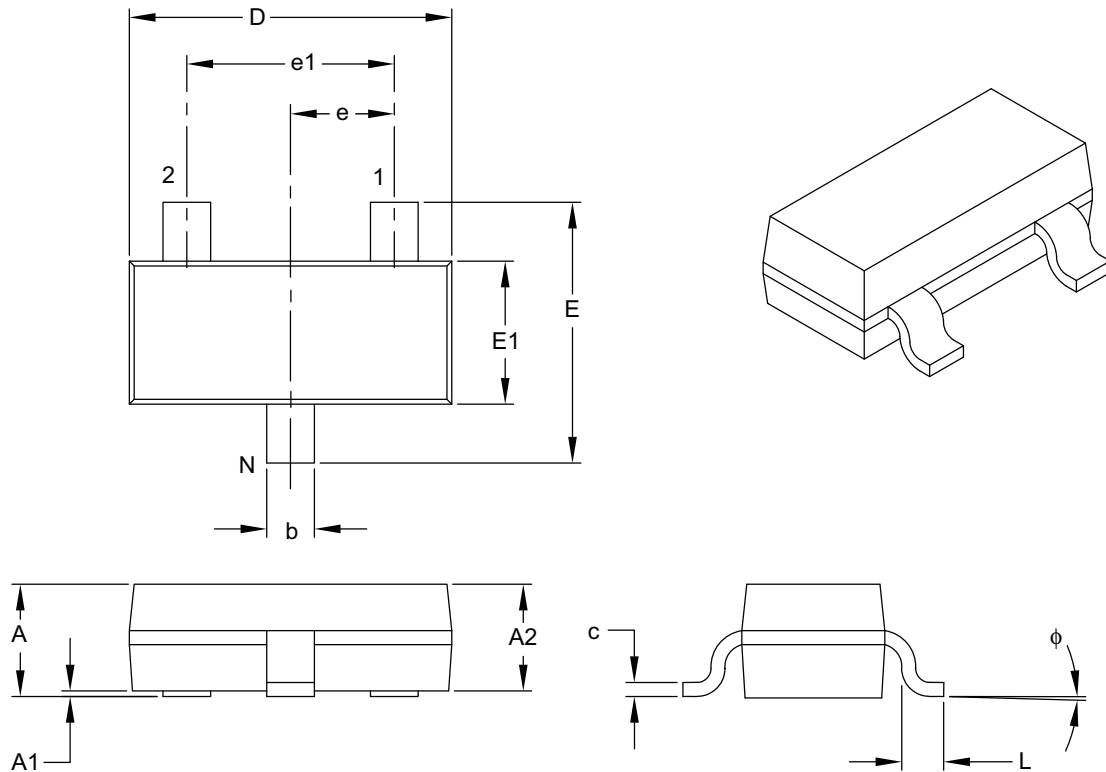


### 3-Lead Plastic Small Outline Transistor (CB) [SOT-23A]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	3		
Lead Pitch	e	0.95 BSC		
Outside Lead Pitch	e1	1.90 BSC		
Overall Height	A	0.89	–	1.45
Molded Package Thickness	A2	0.90	–	1.30
Standoff	A1	0.00	–	0.15
Overall Width	E	2.10	–	3.00
Molded Package Width	E1	1.20	–	1.80
Overall Length	D	2.70	–	3.10
Foot Length	L	0.15	–	0.60
Foot Angle	$\phi$	0°	–	30°
Lead Thickness	c	0.09	–	0.26
Lead Width	b	0.30	–	0.51

**Notes:**

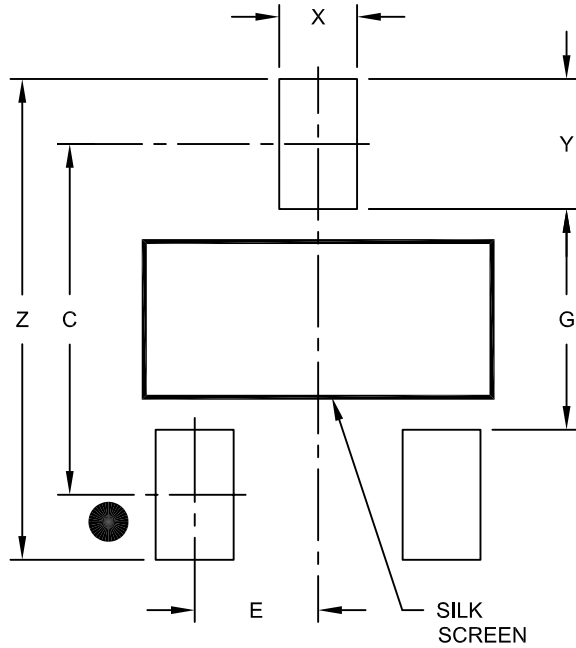
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-130B

3-Lead Plastic Small Outline Transistor (CB) [SOT-23A]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.95 BSC		
Contact Pad Spacing	C		2.70	
Contact Pad Width (X3)	X			0.60
Contact Pad Length (X3)	Y			1.00
Distance Between Pads	G	1.70		
Overall Width	Z			3.70

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2130A